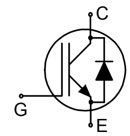
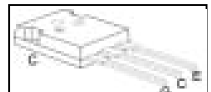
SKW25N120

Fast IGBT in NPT-technology with soft, fast recovery anti-parallel EmCon diode

- 40lower E_{off} compared to previous generation
- Short circuit withstand time – 10 µs
- Designed for:
    - Motor controls
    - Inverter
    - SMPS
- NPT-Technology offers:
    - very tight parameter distribution
    - high ruggedness, temperature stable behaviour
    - parallel switching capability
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC[1] for target applications
- Complete product spectrum and PSpice Models : http://www.infineon.com/igbt/





PG-TO-247-3-21
(TO-247AC)

Type	V_{CE}	I_C	E_{off}	T_j	Marking	Package
SKW25N120	1200V	25A	2.9mJ	150°C	K25N120	PG-TO-247-3-21

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current	I_C		A
T_C = 25°C		46	
T_C = 100°C		25	
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	84	
Turn off safe operating area	-	84	
$V_{CE} \leq$ 1200V, $T_j \leq$ 150°C			
Diode forward current	I_F		
T_C = 25°C		42	
T_C = 100°C		25	
Diode pulsed current, t_p limited by T_{jmax}	I_{Fpuls}	80	
Gate-emitter voltage	V_{GE}	±20	V
Short circuit withstand time[2]	t_{SC}	10	µs
V_{GE} = 15V, 100V≤V_{CC}≤1200V, $T_j \leq$ 150°C			
Power dissipation	P_{tot}	313	W
T_C = 25°C			
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C
Soldering temperature,	T_s	260	
wavesoldering, 1.6mm (0.063 in.) from case for 10s			

[1] J-STD-020 and JESD-022
[2] Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.4	K/W
Diode thermal resistance, junction – case	R_{thJCD}		1.15	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	V_{GE}=0V, I_C=1500µA	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	V_{GE} = 15V, I_C=25A T_j=25°C T_j=150°C	 2.5 -	 3.1 3.7	 3.6 4.3	
Diode forward voltage	V_F	V_{GE}=0V, I_F=25A T_j=25°C T_j=150°C	 -	 2.0 1.75	 2.5 	
Gate-emitter threshold voltage	$V_{GE(th)}$	I_C=1000µA, V_{CE}=V_{GE}	3	4	5	
Zero gate voltage collector current .	I_{CES}	V_{CE}=1200V,V_{GE}=0V T_j=25°C T_j=150°C	 - -	 - -	 350 1400	µA
Gate-emitter leakage current	I_{GES}	V_{CE}=0V,V_{GE}=20V	-	-	100	nA
Transconductance	g_{fs}	V_{CE}=20V, I_C=25A		20	-	S
Dynamic Characteristic						
Input capacitance	C_{iss}	V_{CE}=25V,	-	2150	2600	pF
Output capacitance	C_{oss}	V_{GE}=0V,	-	260	310	
Reverse transfer capacitance	C_{rss}	f=1MHz	-	110	130	
Gate charge	Q_{Gate}	V_{CC}=960V, I_C=25A V_{GE}=15V	-	225	300	nC
Internal emitter inductance Measured 5mm (0.197 in.) from case	L_E		-	13	-	nH
Short circuit collector current[1)]	$I_{C(SC)}$	V_{GE}=15V,t_{SC}≤10µs 100V≤V_{CC}≤1200V, T_j ≤ 150°C	-	240	-	A

[1)] Allowed number of short circuits: <1000; time between short circuits: >1s

Switching Characteristic, Inductive Load, at T_j=25 °C

Parameter	Symbol	Conditions	Value			Unit
			Min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=25°C, V_{CC}=800V, I_C=25A, V_{GE}=15/0V, R_G=22Ω, L_σ[1)]=180nH, C_σ[1)]=40pF Energy losses include "tail" and diode reverse recovery.	-	45	60	ns
Rise time	t_r		-	40	52	
Turn-off delay time	$t_{d(off)}$		-	730	950	
Fall time	t_f		-	30	39	
Turn-on energy	E_{on}		-	2.2	2.9	mJ
Turn-off energy	E_{off}		-	1.5	2.0	
Total switching energy	E_{ts}		-	3.7	4.9	
Anti-Parallel Diode Characteristic						
Diode reverse recovery time	t_{rr} t_S t_F	T_j=25°C, V_R=800V, I_F=25A, di_F/dt=650A/µs	- - -	90		ns
Diode reverse recovery charge	Q_{rr}		-	1.0		µC
Diode peak reverse recovery current	I_{rrm}		-	20		A
Diode peak rate of fall of reverse recovery current during t_F	di_{rr}/dt		-	470		A/µs

Switching Characteristic, Inductive Load, at T_j=150 °C

Parameter	Symbol	Conditions	Value			Unit
			Min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=150°C V_{CC}=800V, I_C=25A, V_{GE}=15/0V, R_G=22Ω, L_σ[1)]=180nH, C_σ[1)]=40pF Energy losses include "tail" and diode reverse recovery.	-	50	60	ns
Rise time	t_r		-	36	43	
Turn-off delay time	$t_{d(off)}$		-	820	990	
Fall time	t_f		-	42	50	
Turn-on energy	E_{on}		-	3.8	4.6	mJ
Turn-off energy	E_{off}		-	2.9	3.8	
Total switching energy	E_{ts}		-	6.7	8.4	
Anti-Parallel Diode Characteristic						
Diode reverse recovery time	t_{rr} t_S t_F	T_j=150°C V_R=800V, I_F=25A, di_F/dt=750A/µs	- - -	280		ns
Diode reverse recovery charge	Q_{rr}		-	4.3		µC
Diode peak reverse recovery current	I_{rrm}		-	32		A
Diode peak rate of fall of reverse recovery current during t_F	di_{rr}/dt		-	130		A/µs

[1)] Leakage inductance L_σ and stray capacity C_σ due to dynamic test circuit in figure E.

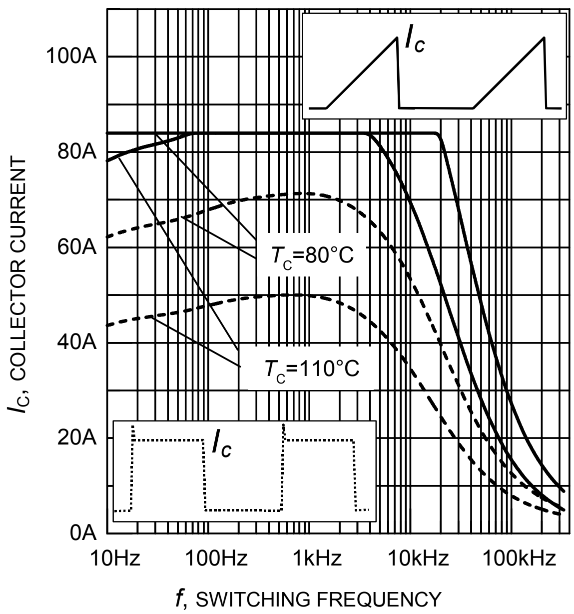


Figure 1. Collector current as a function of switching frequency
($T_j \leq 150°C$, $D = 0.5$, $V_{CE} = 800V$, $V_{GE} = +15V/0V$, $R_G = 22\Omega$)

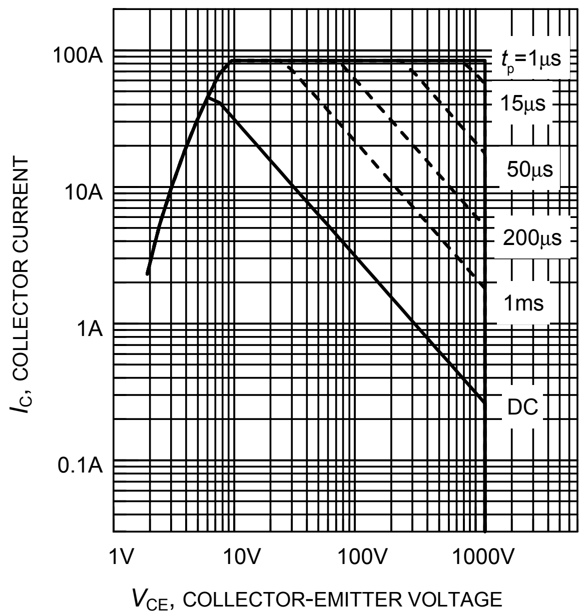


Figure 2. Safe operating area
($D = 0$, $T_C = 25°C$, $T_j \leq 150°C$)

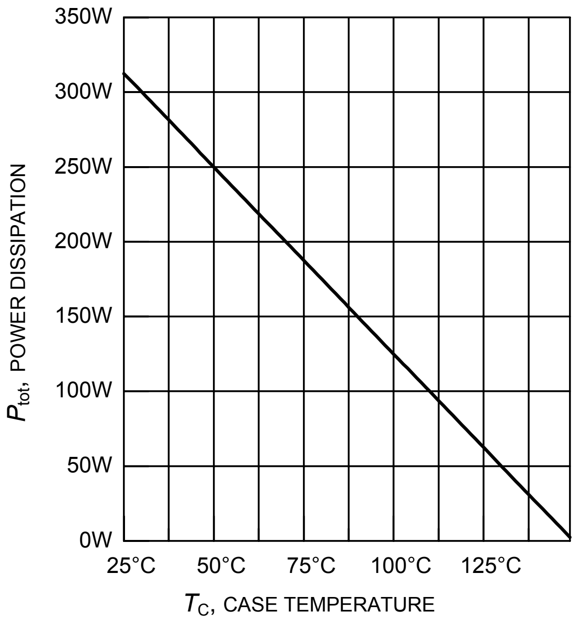


Figure 3. Power dissipation as a function of case temperature
($T_j \leq 150°C$)

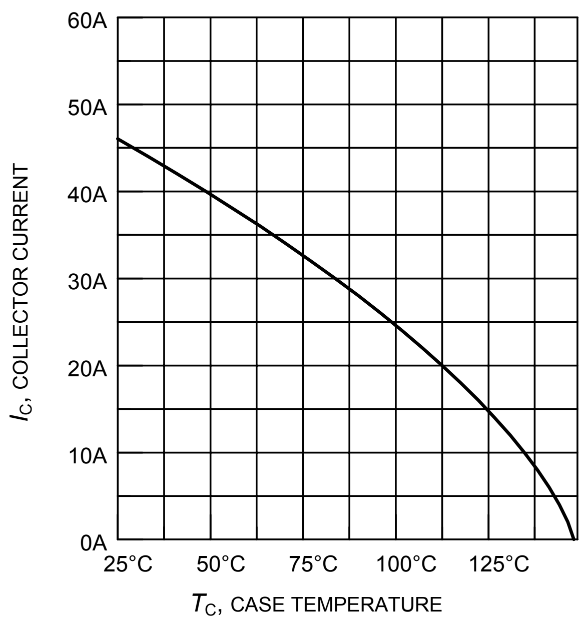


Figure 4. Collector current as a function of case temperature
($V_{GE} \leq 15V$, $T_j \leq 150°C$)

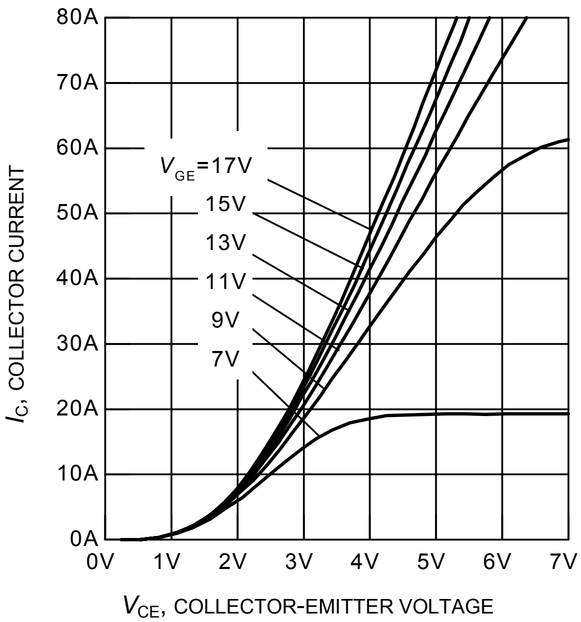


Figure 5. Typical output characteristics
(T_j = 25°C)

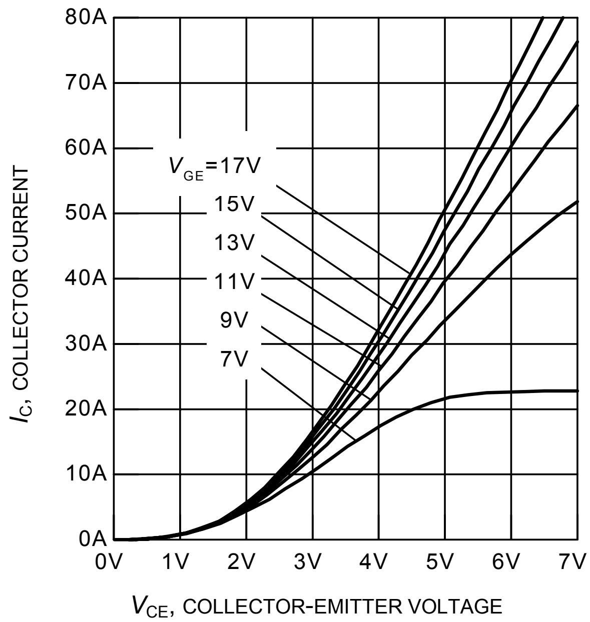


Figure 6. Typical output characteristics
(T_j = 150°C)

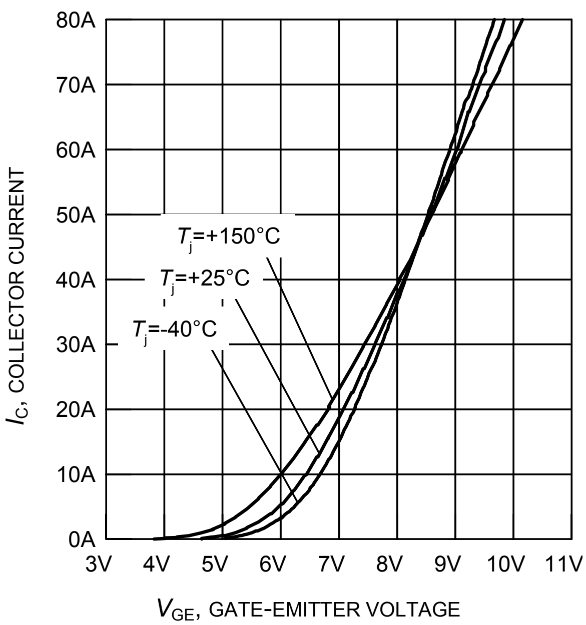


Figure 7. Typical transfer characteristics
(V_{CE} = 20V)

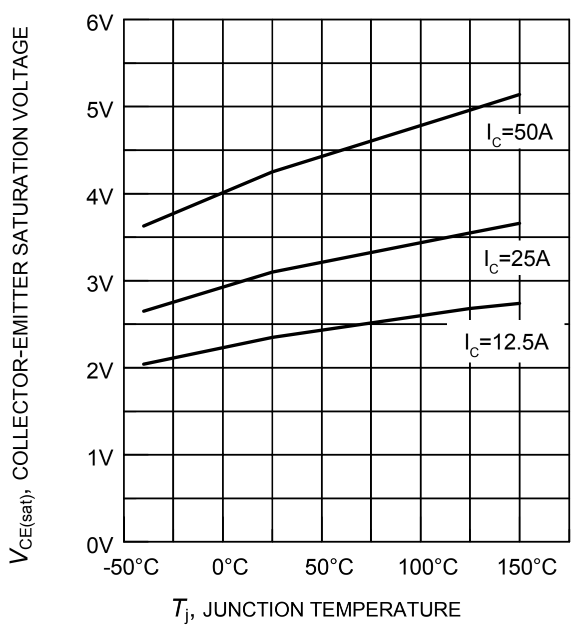


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
(V_{GE} = 15V)

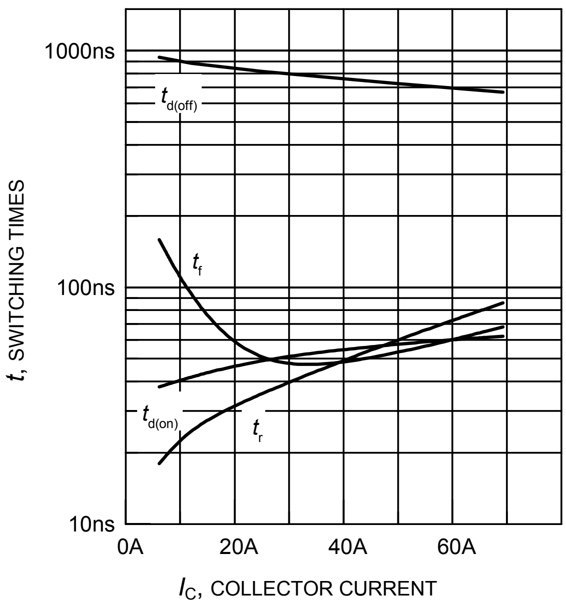


Figure 9. Typical switching times as a function of collector current
(inductive load, T_j = 150°C, V_{CE} = 800V, V_{GE} = +15V/0V, R_G = 22Ω, dynamic test circuit in Fig.E)

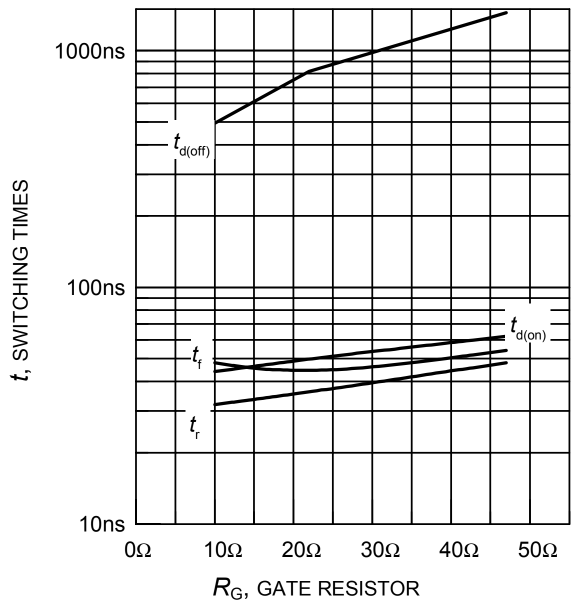


Figure 10. Typical switching times as a function of gate resistor
(inductive load, T_j = 150°C, V_{CE} = 800V, V_{GE} = +15V/0V, I_C = 25A, dynamic test circuit in Fig.E)

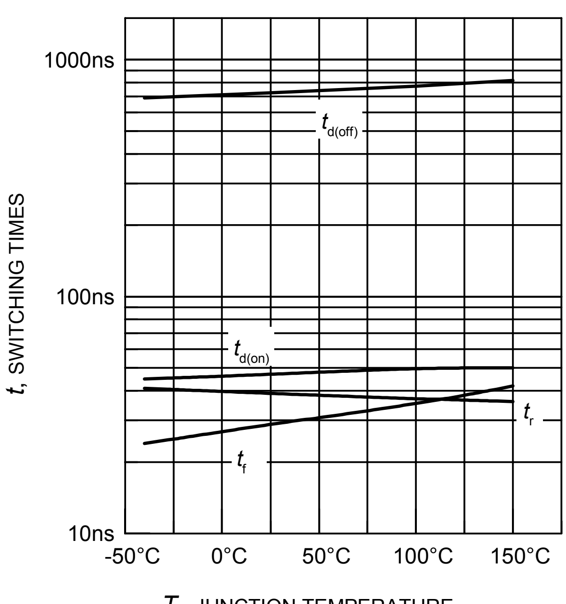


Figure 11. Typical switching times as a function of junction temperature
(inductive load, V_{CE} = 800V, V_{GE} = +15V/0V, I_C = 25A, R_G = 22Ω, dynamic test circuit in Fig.E)

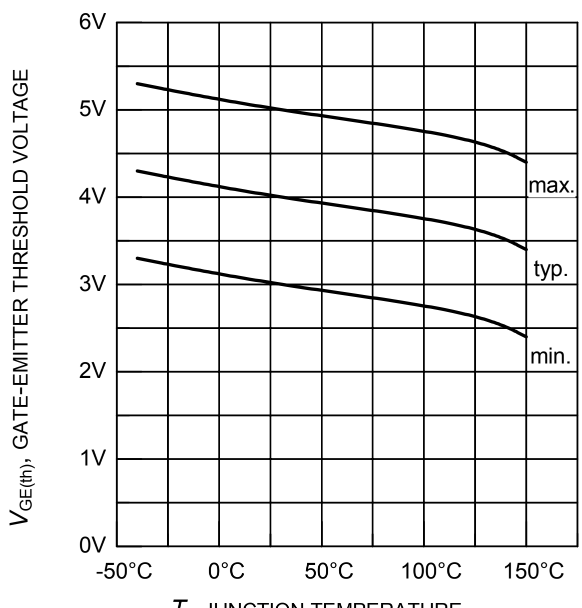


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
(I_C = 0.3mA)

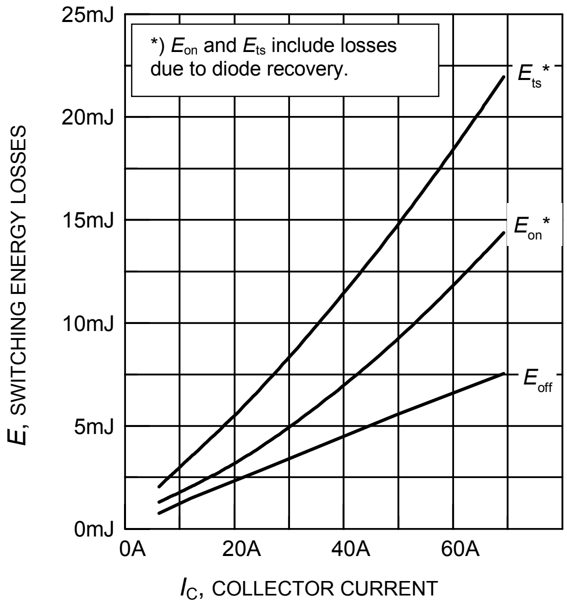


Figure 13. Typical switching energy losses as a function of collector current
(inductive load, T_j = 150°C,
V_{CE} = 800V, V_{GE} = +15V/0V, R_G = 22Ω,
dynamic test circuit in Fig.E)

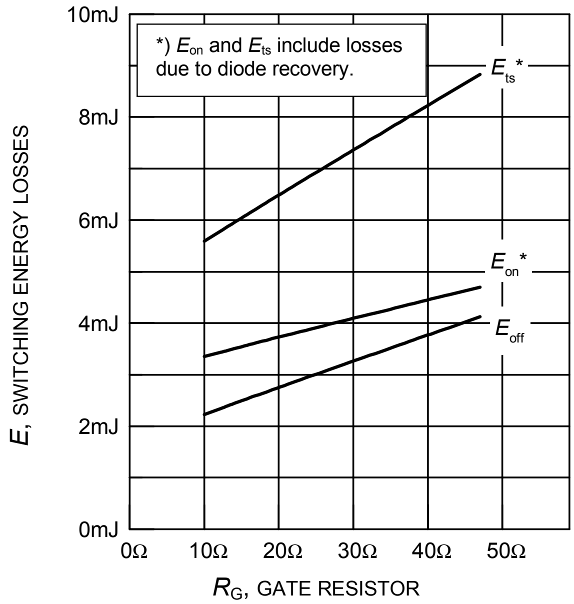


Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, T_j = 150°C,
V_{CE} = 800V, V_{GE} = +15V/0V, I_C = 25A,
dynamic test circuit in Fig.E)

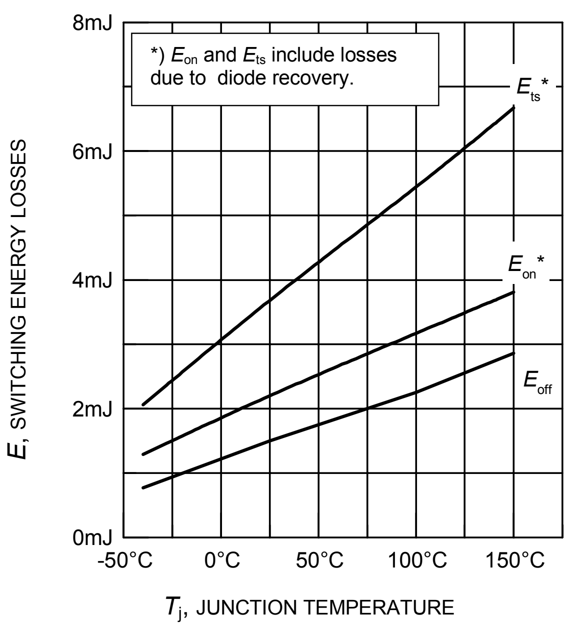


Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, V_{CE} = 800V,
V_{GE} = +15V/0V, I_C = 25A, R_G = 22Ω,
dynamic test circuit in Fig.E)

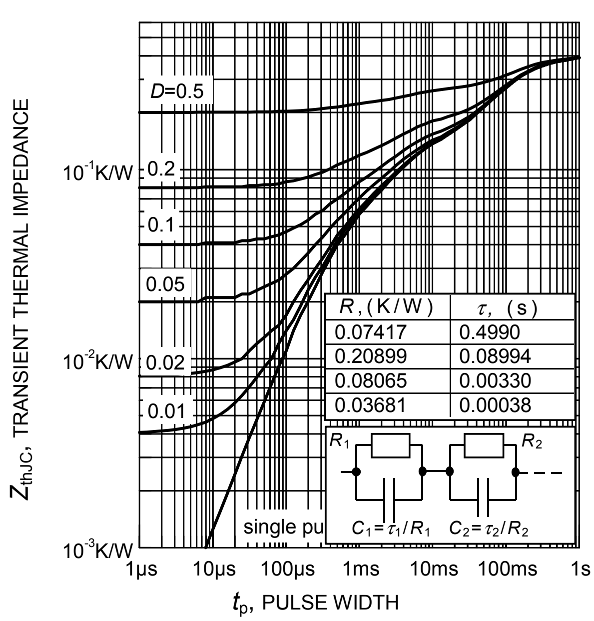


Figure 16. IGBT transient thermal impedance as a function of pulse width
($D = t_p$ / T)

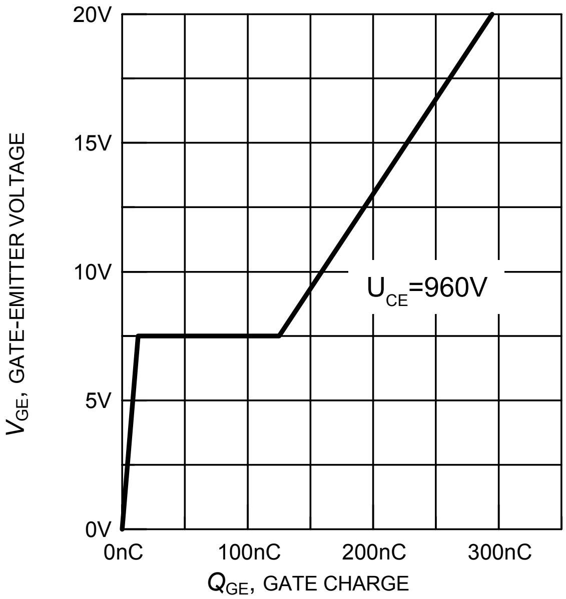


Figure 17. Typical gate charge
(I_C = 25A)

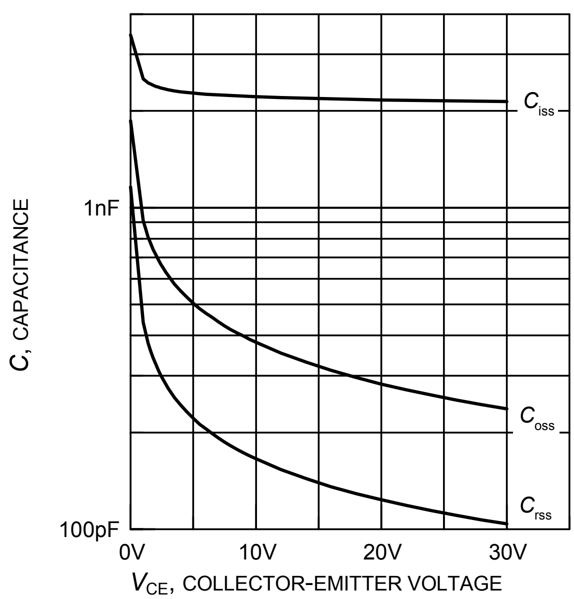


Figure 18. Typical capacitance as a function of collector-emitter voltage
(V_{GE} = 0V, f = 1MHz)

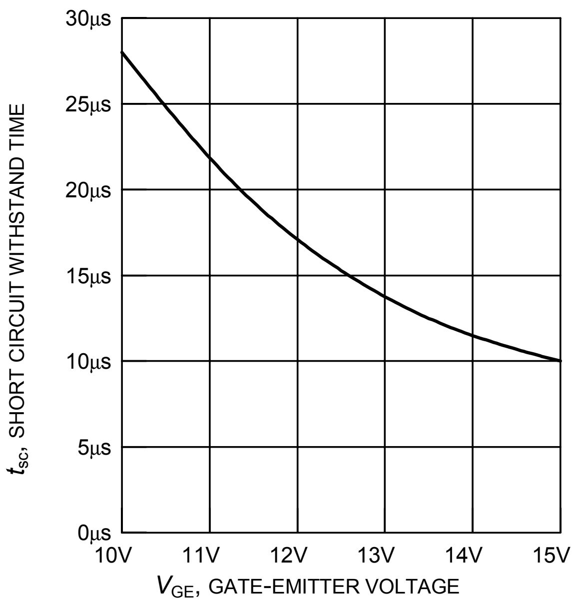


Figure 19. Short circuit withstand time as a function of gate-emitter voltage
(V_{CE} = 1200V, start at T_j = 25°C)

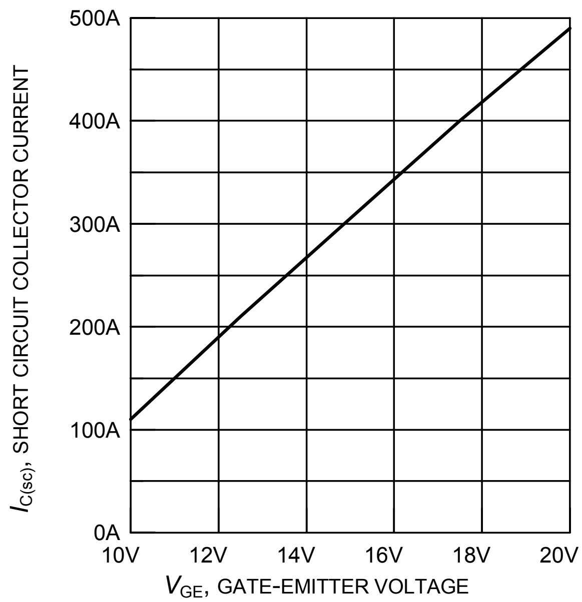


Figure 20. Typical short circuit collector current as a function of gate-emitter voltage
(100V≤V_{CE} ≤1200V, T_C = 25°C, T_j ≤ 150°C)

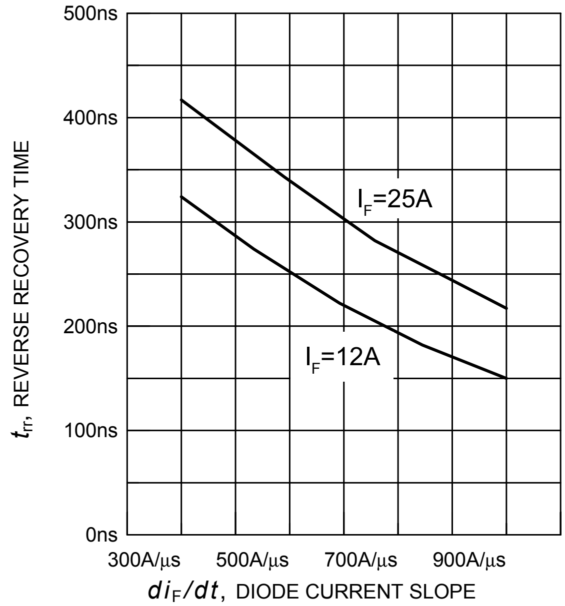


Figure 21. Typical reverse recovery time as a function of diode current slope
(V_R = 800V, T_j = 150°C,
dynamic test circuit in Fig.E)

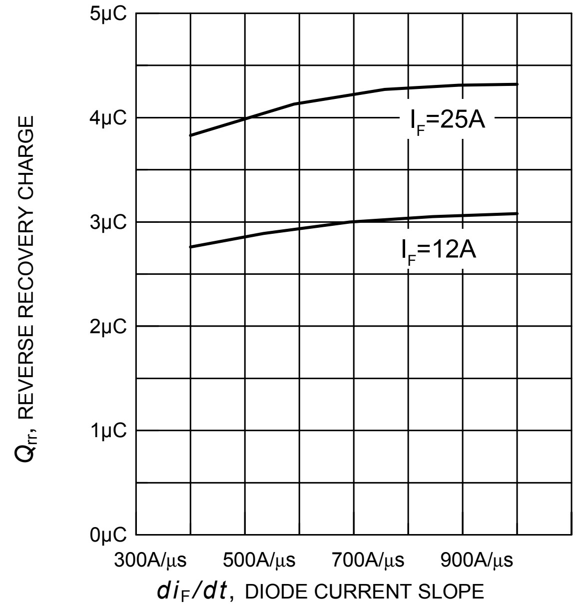


Figure 22. Typical reverse recovery charge as a function of diode current slope
(V_R = 800V, T_j = 150°C,
dynamic test circuit in Fig.E)

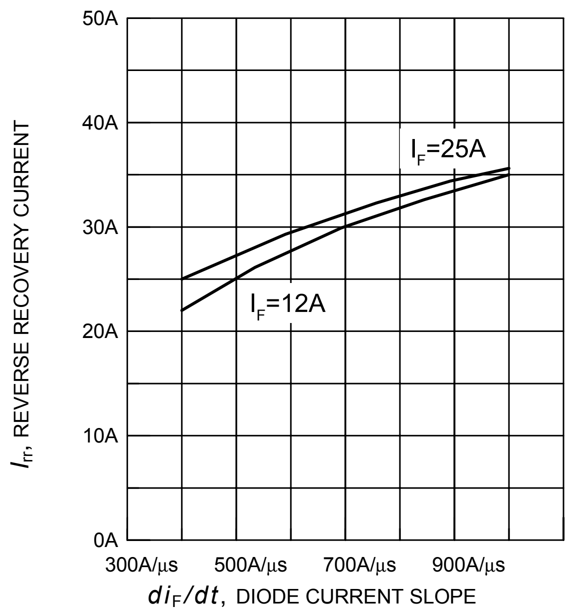


Figure 23. Typical reverse recovery current as a function of diode current slope
(V_R = 800V, T_j = 150°C,
dynamic test circuit in Fig.E)

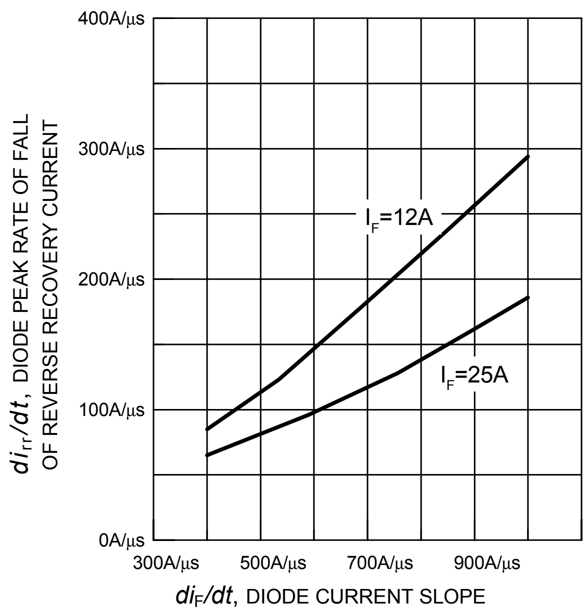


Figure 24. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope
(V_R = 800V, T_j = 150°C,
dynamic test circuit in Fig.E)

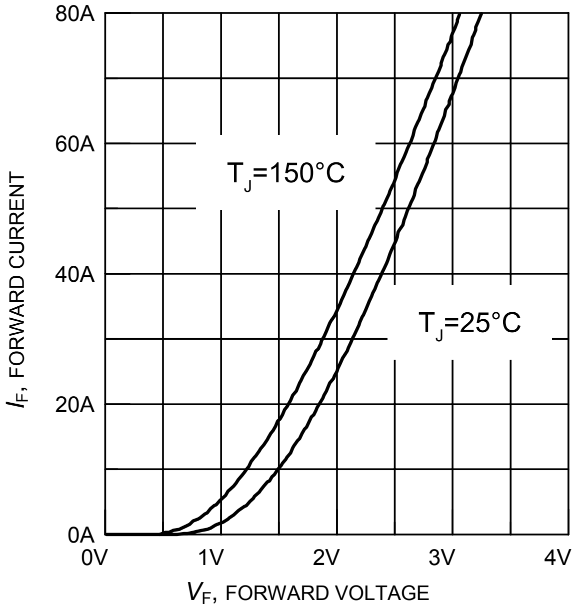


Figure 25. Typical diode forward current as a function of forward voltage

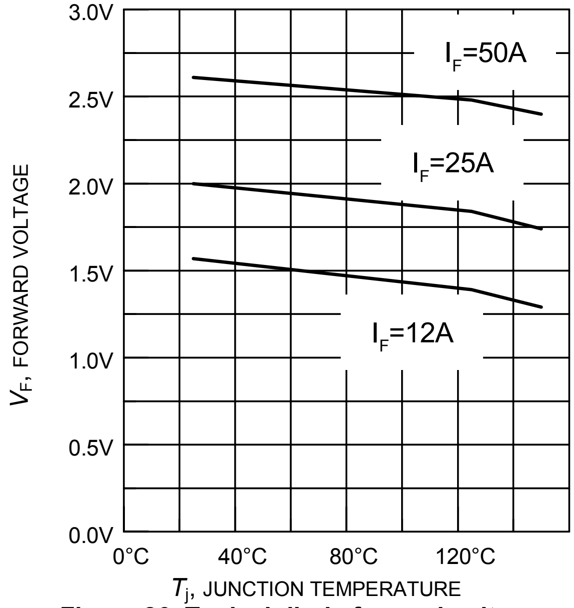


Figure 26. Typical diode forward voltage as a function of junction temperature

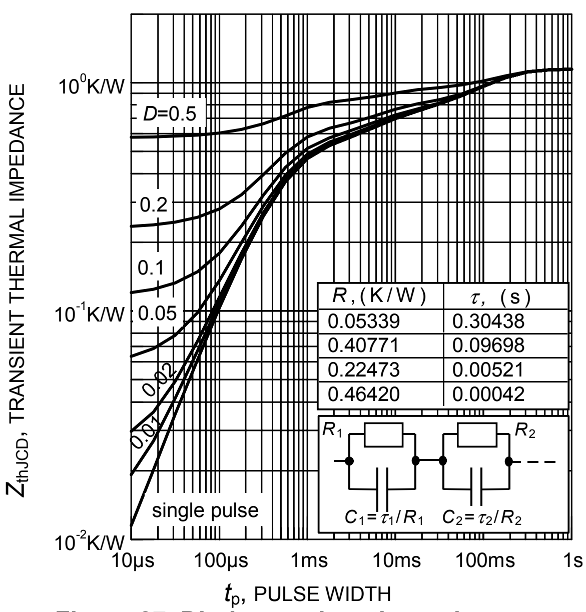


Figure 27. Diode transient thermal impedance as a function of pulse width
($D = t_p / T$)

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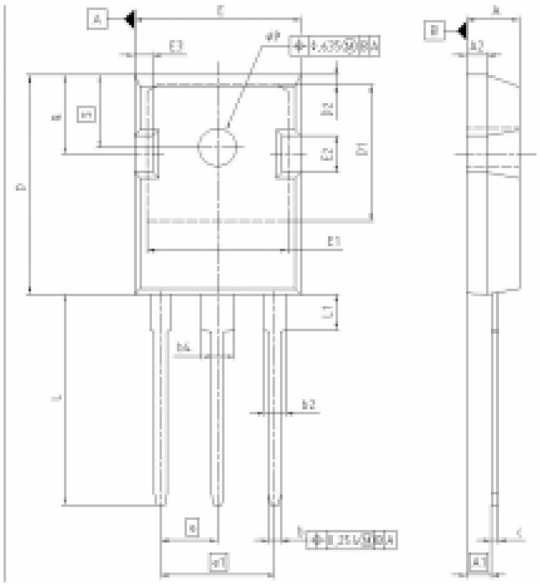

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.092	0.098
A2	1.853	2.107	0.075	0.081
b	1.073	1.327	0.047	0.052
b2	1.903	2.386	0.075	0.094
b4	2.870	3.454	0.113	0.136
c	0.549	0.752	0.024	0.030
D	20.823	21.077	0.820	0.830
D1	17.323	17.831	0.682	0.702
D2	1.083	1.317	0.042	0.052
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
E2	3.683	3.937	0.145	0.155
E3	1.683	1.937	0.066	0.076
e	5.450		0.215	
e1	10.900		0.430	
N	3		3	
L	20.053	20.307	0.789	0.799
L1	4.188	4.472	0.164	0.176
øP	3.559	3.661	0.140	0.144
Q	5.490	5.747	0.216	0.226
S	6.043	6.297	0.238	0.248

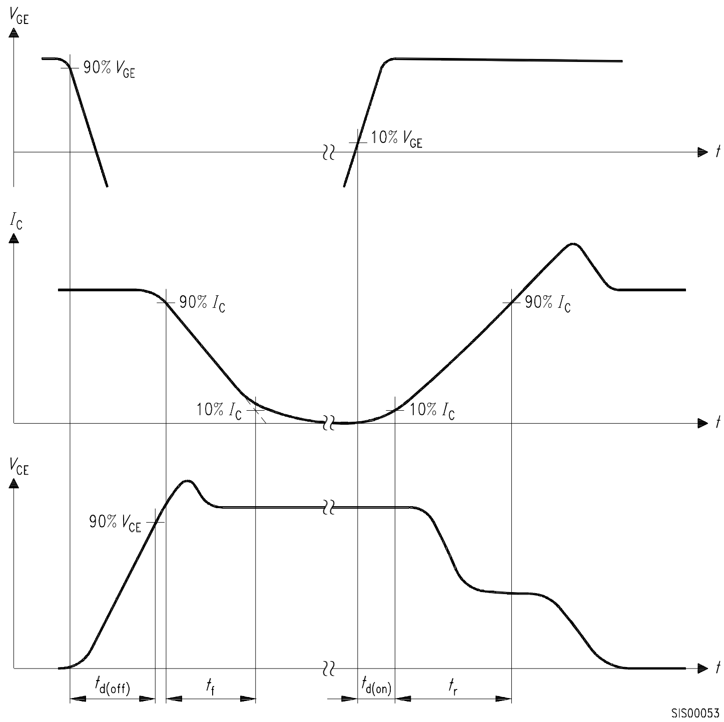

Figure A. Definition of switching times

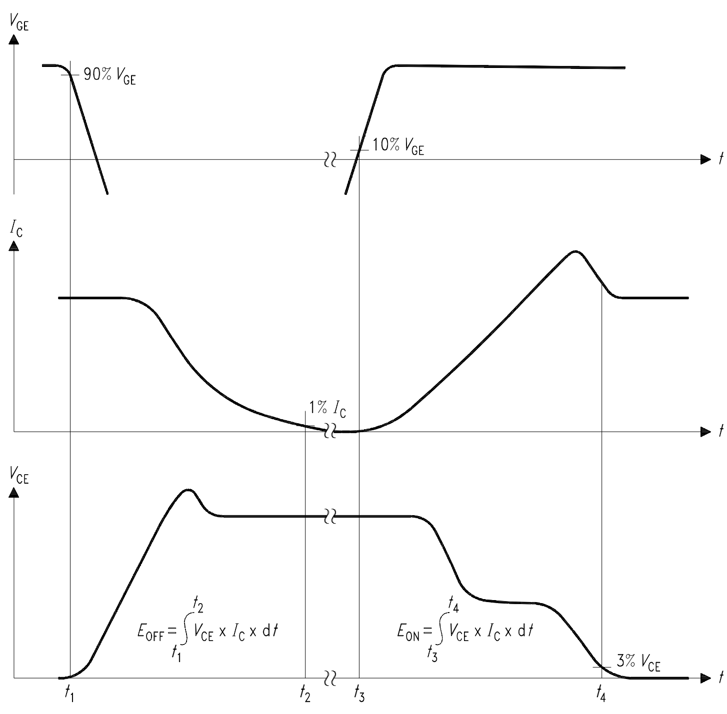

Figure B. Definition of switching losses

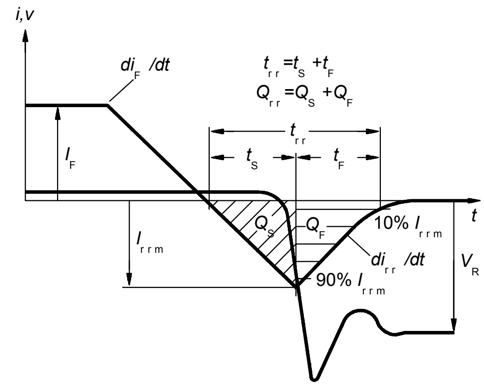

Figure C. Definition of diodes switching characteristics

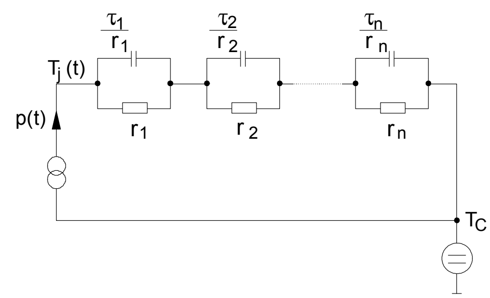

Figure D. Thermal equivalent circuit

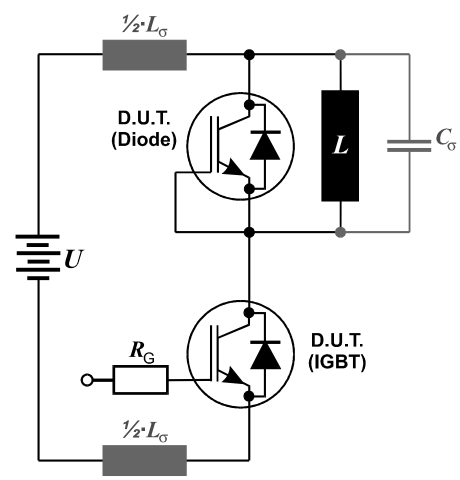

Figure E. Dynamic test circuit
Leakage inductance L_σ=180nH,
and stray capacity C_σ=40pF.

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